

S3ABF THRU S3MBF

Reverse Voltage – 50 to 1000 V
Forward Current – 3 A

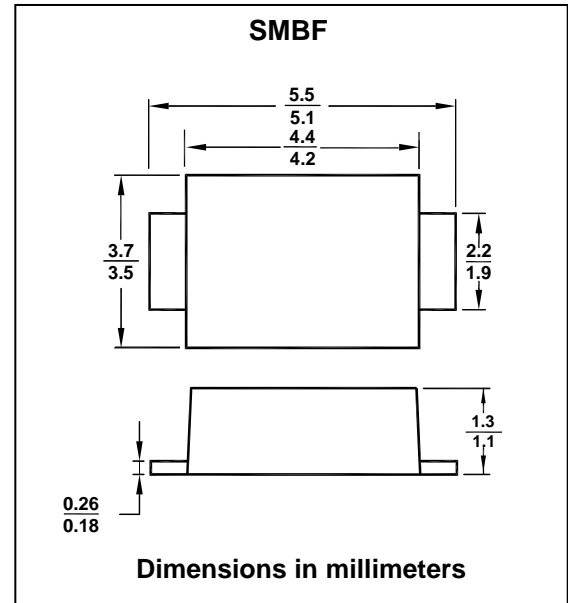
Features

- Glass Passivated Chip Junction
- For surface mount applications
- Low profile package
- Easy pick and place

Mechanical Data

- **Case:** SMBF
- **Terminals:** Solderable per MIL-STD-750, method 2026

SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER



Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	S3ABF	S3BBF	S3DBF	S3GBF	S3JBF	S3KBF	S3MBF	Units
	Marking	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	-
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 65^\circ\text{C}$	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	100							A
Maximum Forward Voltage at 3 A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25^\circ\text{C}$ $T_a = 125^\circ\text{C}$	I_R	5 200							μA
Typical Junction Capacitance ¹⁾	C_J	45							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	40							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150							$^\circ\text{C}$

¹⁾ Measured at 1MHz and applied reverse voltage of 4 V D.C.

²⁾ P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.

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Fig.1 Forward Current Derating Curve

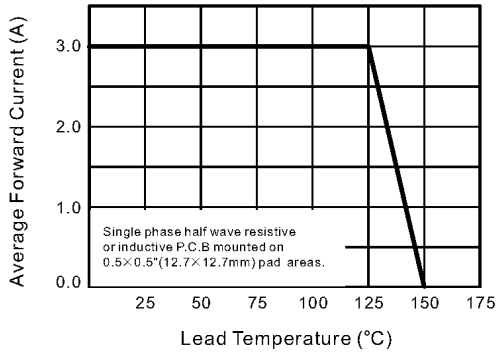


Fig.2 Typical Reverse Characteristics

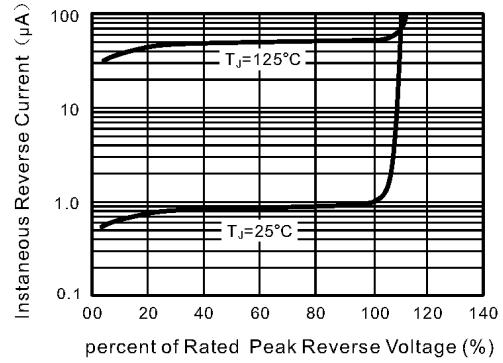


Fig.3 Typical Instantaneous Forward Characteristics

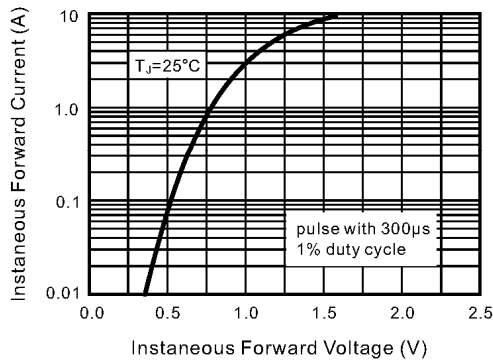


Fig.4 Typical Junction Capacitance

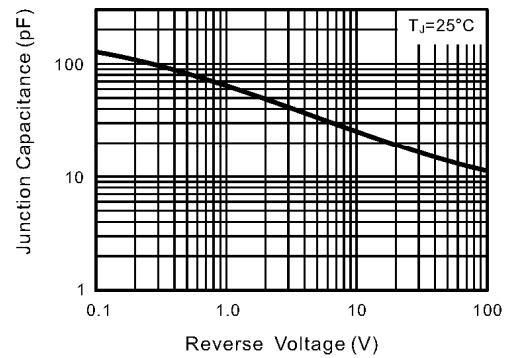


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

